For 0.005" traces on all layers:
10. Trace Inductance: 350 nH per 5" trace.
9. Silk screening on both sides.
8. Board thickness and inner-layer spacing as specified.
7. Epoxy thickness: 0.002".
5. 1/2 oz copper for embedded signal layers.
4. Min. clearance: 0.006" on all layers.
3. Min. trace width: 0.006" on all layers.
1. Dimensions are given in inches and mm.

Board Characteristics

Layer Order:
1. Signal-1
2. Power-1 VCC
3. Signal-2
4. Signal-3
5. Power-4 GND
6. Signal-4

Board Specifications:

- Dimensions: 100 x 100 x 0.3 mm
- Thickness: 0.3 mm
- Material: FR-4
- Silk screening on both sides
- Trace Inductance: 350 nH per 5" trace
- Min. clearance: 0.006" on all layers
- Min. trace width: 0.006" on all layers
- Electroless Nickel/Imersion Gold Plating. Apply soldermask
- 1/2 oz copper for embedded signal layers
- Material: FR-4

Specifications:

- Dimensions: 100 x 100 x 0.3 mm
- Thickness: 0.3 mm
- Material: FR-4
- Silk screening on both sides
- Trace Inductance: 350 nH per 5" trace
- Min. clearance: 0.006" on all layers
- Min. trace width: 0.006" on all layers
- Electroless Nickel/Imersion Gold Plating. Apply soldermask
- 1/2 oz copper for embedded signal layers
- Material: FR-4